

<b>Product Specification(产品规格书)</b>	<b>Issued By: Engineering Dept.</b>	
<b>Subject (主题):</b> 0.80mm Pitch KR0803 Series wire to board Connector Specification	<b>Date Issued</b>	2022/2/26
	<b>Date Revised</b>	2022/2/26
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**1.0 适用范围 (Scope)**

此种规格包括1.00mm Pitch KR1007 Series 连接器规格说明.

This Specification Covers the 1.00mm Pitch KR1007 Series Connector Specification.

**2.0 规格与料号 (Spec and Part number)**

规格内容 <b>Specification</b>	产品料号 <b>Production No.</b>	产品图示 <b>Picture of Product</b>
胶壳/Housing	H100702**0101A	
端子/Terminal	T10070PG0101A	
针座/Wafer	C1007VS2**13G0101RA	

**3.0 材质与表面处理 (Disposal of Material and surface)**

规格内容 <b>Specification</b>		材质 <b>Materials</b>	表面处理 <b>Disposal of Surface</b>	
胶壳/Housing		PA66	UL94 V-0	
端子/Terminal		Phosphor Bronze	Gold flash plated over Nickel	
针座/ Wafer	立式 Straight (SMT 180° )	主体 Base	LCP	UL94 V-0
		导体 Contact	Phosphor bronze	Gold flash plated over Nickel
		固定片 Solder tab	Brass	Gold flash plated over Nickel
	卧式 Right Angle (SMT 90° )	主体 Base	N/A	N/A
		导体 Contact	N/A	N/A
		固定片 Solder tab	N/A	N/A

(以上参数请以工程图为准/Please Refer to the Project drawing for the above Specification)

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**4.0 额定等级 (Ratings and applicable wires)**

项 目 Item	规 格 Standard	
额定电压Rated Voltage (Max.)	50V	AC/DC
额定电流Rated Current (Max.)	1A(28AWG)	
使用温度范围Ambient temperature Range	-40°C~+105°C	
适用线径Applicable wire insulation O.D	AWG 28#~32# Insulation O.D. 0.40 to 0.80mm	

**5.0 电气性能 (Electrical Performance)**

项 目 Item	条 件 Test Condition	规 格 Requirement
5.1 接触阻抗 Contact Resistance	公母配合,开放电压 20mV 最大,电流 100mA最大 检测连接器A~B 区. Mate connectors, measure by dry circuit, 20mV MAX, 100mA MAX. (Based upon EIA-364-23C)	55 milliohms Max.
5.2 绝缘阻抗 Insulation Resistance	公母配合,对相邻两接触导体,于1分钟内施 加500V 的直流电,并量测其间绝缘阻抗. Mate connectors, apply 500V DC for 1 minute between adjacent contacts to measure the insulation resistance. (Based upon EIA-364-21B)	500 Megohms Min.
5.3 耐电压 Dielectric Strength	公母配合,在相邻端子或端子与接地端之 间,使用300V 的交流电1 分钟,检测连接器. Mate connectors, apply 300V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A)	无损毁或出现电火花 No Breakdown and Flashover

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**6.0 机械性能 (Mechanical Performance)**

项 目 Item		条 件 Test Condition		规 格 Requirement		
6.1	插拔力 Insertion & Withdrawal Force	以每分钟25.4±3mm的速率插入和拔出。 (不包含卡榫结合力) Insert and withdraw connectors at the speed rate of 25.4±3mm/minute. (Excluding plastic detents) (Based upon EIA-364-13D)		参照第8.0项 Refer to paragraph 8.0		
6.2	端子插入力 Terminal Insertion Force	铆线后之端子插入 Housing 所需最大力量。 Insert the crimped terminal into the housing.		0.5 kgf (4.9 N) Max.		
6.3	端子保持力 Terminal/Housing Retention Force	以每分钟 25.4±3mm 的速率,将端子从 Housing内轴向拔出的力量。 Apply axial pull out force at the speed rate of 25.4±3mm/minute on the terminal assembled in the housing.		0.6 kgf (5.88 N) Min.		
6.4	Pin 针保持力 Pin Retention Force	以每分钟 25.4±3mm 的速率,将PIN针从 Wafer 内轴向拔出的力量。 Apply axial push force at the speed rate of 25.4±3mm/minute.		0.4 kgf (3.92 N) min.		
6.5	端子压接 Terminal Crimping Specification	Wire Size		28 AWG	30 AWG	32 AWG
		①	Crimp width	0.75 Max.		
			Crimp height	0.55~0.50	0.50~0.45	0.45~0.40
		②	Crimp width	0.80 Max.		
			Crimp height	0.95 Max	0.90 Max	0.80 Max
		Crimp strength (kgf)		1.36 Min.	0.9 Min.	0.7 Min.
		Stripping(mm)		1.2-1.6		
① Conductor(mm) ② Insulation(mm)						

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**7.0 环境性能及其它 (Environmental Performance and Others)**

项 目 Item		条 件 Test Condition	规 格 Requirement	
7.1	耐久性 Durability	以每分钟不超过 10 次的速率,将公母插拔30次. When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute. (Based upon EIA-364-09C)	接触阻抗 Contact Resistance	75 milliohms Max.
7.2	温升测试 Temperature Rise	公母对插后,在通过额定电流下,所测定的温度. Carrying rated current load. (Based upon EIA-364-70B)	温升测试 Temperature Rise	30°C Max.
7.3	耐振动性 Vibration	振幅: 1.5mm P-P 时间: 10~55~10 HZ in 1 minute 持续时间: 每轴向 2 小时 Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.
7.4	耐冲击性 Shock	在 X.Y.Z 上 6 个方向上,以 490m/s <sup>2</sup> (50g) 冲击下各 3 回. 490m/s <sup>2</sup> {50g}, 3strokes in each X.Y.Z. axes. (Based upon EIA-364-27B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.
7.5	耐热性 Heat Resistance	105±2°C,96 hours. (Based upon EIA-364-17B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.
7.6	耐寒性 Cold Resistance	-40±2°C,96 hours. ( Based upon EIA-364-59)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.

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7.7	耐湿性 Humidity	温度: 40±2°C 湿度: 90~95%(RH) 持续时间: 96 hours Temperature: 40±2°C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.
			耐电压 Dielectric Strength	Must meet 5.3
			绝缘阻抗 Insulation Resistance	100 Megohms Min.
7.8	热冲击 Thermal shock	以-40°C持续30分钟经室温5分钟,而后以105°C持续30分钟再经室温5分钟为一个循环,共循环5次. One Cycle Consists Of: -40°C for 30 minutes. → Room Temp. 5 minutes, +105°C for 30minutes. → Room Temp. 5 minutes Total Cycles: 5 Cycles. (Based upon EIA-364-32B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.
7.9	盐水喷雾 Salt Spray	在温度35±2°C,盐水浓度5±1%下,盐水喷雾24小时. 24 hours exposure to a salt spray from the 5±1% solution at 35±2°C. (Based upon EIA-364-26B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	75 milliohms Max.
7.10	焊锡附着性 Solder-ability	焊接时间: 3±0.5 秒. 焊接温度: 245±5°C. Soldering Time: 3±0.5second. Solder Temperature: 245±5°C. (Based upon EIA-364-52)	Solder Wetting	浸渍面积需95%以上 95% of immersed area must show no voids, pin holes.

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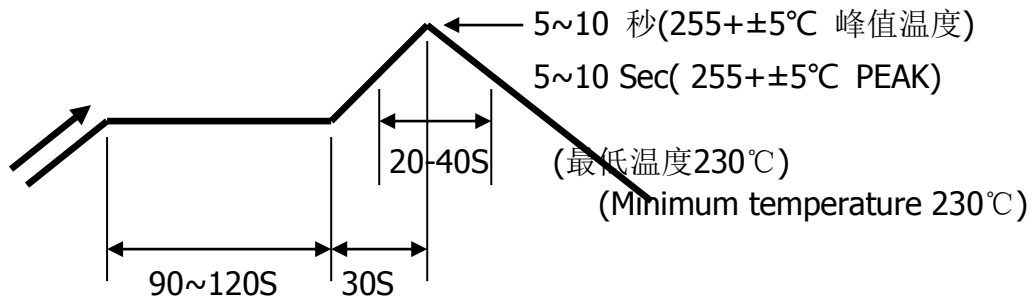
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7.11	焊锡耐热性 Solder-Resistance	SMT型产品，能够承受焊锡耐热范围。 SMT type products, able to withstand the solder heat resistance range. 参考温度曲线图9.0 Refer to Temperature Profile9.0 (Based upon EIA-364-56D)	外观 Appearance	无异状 No Damage

**8.0 综合插入力及拔出力 (Insertion/withdrawal force)**  
<Unit: kgf>

No. of Circuits PIN数	At Initial 首次插入与拔出力 (初始值)		At 30 <sup>th</sup> 30次插入 与拔出后	No. of Circuits PIN数	At Initial 首次插入与拔出力 (初始值)		At 30 <sup>th</sup> 30次插入与 拔出后
	I.F.(MAX.) 插入力	R.F.(MIN.) 拔出力	R.F.(MIN.) 拔出力		I.F.(MAX.) 插入力	R.F.(MIN.) 拔出力	R.F.(MIN.) 拔出力
2x3	2.50	0.18	0.13	2x15	3.50	0.45	0.35
2x5	2.50	0.20	0.15	2x20	4.00	0.60	0.50
2x6	2.60	0.21	0.16	2x25	4.50	0.75	0.65
2x10	3.00	0.30	0.20				

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**9.0 SMT 红外线回流条件 (SMT INFRARED REFLOW CONDITION)**



预热 150~200°C) (Reflow)  
(Pre-heat 150~200°C)

温度条件曲线图/ 基板上温度

TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON BOARD PATTERN SIDE)

注: 由于P.C板等焊接装置改变条件,所以请预先用自己的装置检查回流焊的条件.

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.

**10.0 备注 (Remark)**

有关规格书内容经变更或改版,如未能及时发布与通知,烦请联系我司业务人员提供产品最新资讯

Any change or revision for the product specification will not be announced in advance.

Please contact our sales representative for the latest information.

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